		,	-		Docket Number		Application N	umber			
INFORMATION DISCLOSURE CITATION IN AN APPLICATION					M4065.0127/P1	Not Yet Assigned					
					Applicant(s)						
					Kie Y. Ahn et al.						
					Filing Date Group Art Unit						
					September 12, 2000		2815				
					2010						
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*EXAMINER INITIAL	REF	DOCUMENT NO.	DATE		NAME	CLASS	SUBCLASS	FILING II APPROI	PRIATE		
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EXAMINER: Initial if citation considered, whether	or not citation is in conformance with MPEP Section 609; Draw line through	وباد
citation if not in conformance and not considered.	Include convocinis ionii with next communication to Addition.	22
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DATE CONSIDERED